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Soft soldering fluxes - Test methods - Part 5: Copper mirror test (ISO 9455-5:2014)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/15

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English Version

**Soft soldering fluxes - Test methods - Part 5: Copper mirror test
(ISO 9455-5:2014)**Flux de brasage tendre - Méthodes d'essai - Partie 5: Essai
au miroir de cuivre (ISO 9455-5:2014)Flussmittel zum Weichlöten - Prüfverfahren - Teil 5:
Kupferspiegeltest (ISO 9455-5:2014)

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EUROPEAN COMMITTEE FOR STANDARDIZATION
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EUROPÄISCHES KOMITEE FÜR NORMUNG**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

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Foreword

This document (EN ISO 9455-5:2014) has been prepared by Technical Committee ISO/TC 44 "Welding and allied processes" in collaboration with Technical Committee CEN/TC 121 "Welding and allied processes" the secretariat of which is held by DIN.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by January 2015, and conflicting national standards shall be withdrawn at the latest by January 2015.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document supersedes EN 29455-5:1993.

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

Endorsement notice

The text of ISO 9455-5:2014 has been approved by CEN as EN ISO 9455-5:2014 without any modification.

**Soft soldering fluxes — Test
methods —**

**Part 5:
Copper mirror test**

*Flux de brasage tendre — Méthodes d'essai —
Partie 5: Essai au miroir de cuivre*





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ISO copyright office
Case postale 56 • CH-1211 Geneva 20
Tel. + 41 22 749 01 11
Fax + 41 22 749 09 47
E-mail copyright@iso.org
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Foreword

ISO (the International Organization for Standardization) is a worldwide federation of national standards bodies (ISO member bodies). The work of preparing International Standards is normally carried out through ISO technical committees. Each member body interested in a subject for which a technical committee has been established has the right to be represented on that committee. International organizations, governmental and non-governmental, in liaison with ISO, also take part in the work. ISO collaborates closely with the International Electrotechnical Commission (IEC) on all matters of electrotechnical standardization.

The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular the different approval criteria needed for the different types of ISO documents should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2 (see www.iso.org/directives).

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For an explanation on the meaning of ISO specific terms and expressions related to conformity assessment, as well as information about ISO's adherence to the WTO principles in the Technical Barriers to Trade (TBT) see the following URL: Foreword - Supplementary information

The committee responsible for this document is ISO/TC 44, *Welding and allied processes*, Subcommittee SC 12, *Soldering materials*.

This second edition cancels and replaces the first edition (ISO 9455-5:1992), which has been technically revised.

Requests for official interpretations of any aspect of this International Standard should be directed to the Secretariat of ISO/TC 44/SC 12 via your national standards body. A complete listing of these bodies can be found at www.iso.org.

ISO 9455 consists of the following parts, under the general title *Soft soldering fluxes — Test methods*:

- *Part 1: Determination of non-volatile matter, gravimetric method*
- *Part 2: Determination of non-volatile matter, ebulliometric method*
- *Part 3: Determination of acid value, potentiometric and visual titration methods*
- *Part 5: Copper mirror test*
- *Part 6: Determination and detection of halide (excluding fluoride) content*
- *Part 8: Determination of zinc content*
- *Part 9: Determination of ammonia content*
- *Part 10: Flux efficacy test, solder spread method*
- *Part 11: Solubility of flux residues*
- *Part 13: Determination of flux spattering*
- *Part 14: Assessment of tackiness of flux residues*
- *Part 15: Copper corrosion test*

- *Part 16: Flux efficacy tests, wetting balance method*
- *Part 17: Surface insulation resistance comb test and electrochemical migration test of flux residues*

Soft soldering fluxes — Test methods —

Part 5: Copper mirror test

1 Scope

This part of ISO 9455 specifies a qualitative method for assessing the aggressiveness of a flux towards copper. The test is applicable to all fluxes of type 1 as defined in ISO 9454-1.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO 9454-1, *Soft soldering fluxes — Classification and requirements — Part 1: Classification, labelling and packaging*

ISO 9455-1, *Soft soldering fluxes — Test methods — Part 1: Determination of non-volatile matter, gravimetric method*

ISO 9455-2, *Soft soldering fluxes — Test methods — Part 2: Determination of non-volatile matter, ebulliometric method*

koniec náhľadu – text ďalej pokračuje v platenej verzii STN